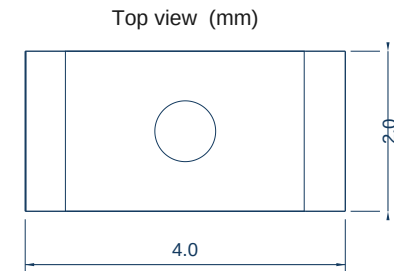
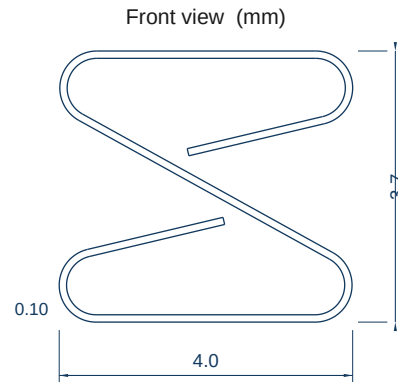
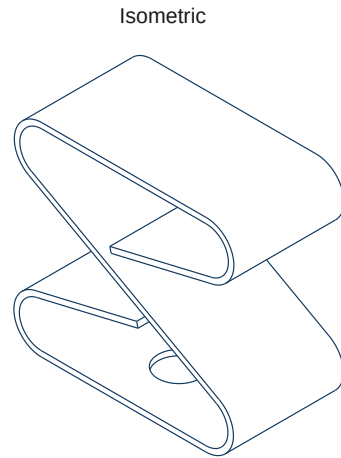




Type 8-01 B801-20040037

SMD EMI Spring Contact | Beryllium Copper | Units: mm



MECHANICAL	VALUE
Thickness	0.10 mm
Width	2.0 mm +/- 0.2
Length	4.0 mm +/- 0.2
Height	3.7 mm +/- 0.2
Form	Z-form: 2 plates + diagonal web + 2 return stubs, 180 deg rot. sym.
Outer curls	R0.452 CL, 167 deg (x2)
Inner curls	R0.455 CL, 151 deg (x2)
Diagonal web	3.90 mm at 29 deg to the plates
Base hole	dia 0.76 mm, centred (2.0 from each end)
Developed length	18.69 mm
Material / plating	BeCu, Gold-plated (G)
Volume / mass	3.693 mm ³ 30.9 mg (BeCu)
File format	STEP AP214

PRODUCT DATA	VALUE
Mfr P/N	B801-20040037G-SY (Au)
Brand	Seyunda
Description	SMD EMI Contact 4.0x2.0x3.7mm Au
Packaging	Tape & Reel (TR)
Category	Connectors, Interconnects
Sub-category	Contacts, Spring Loaded (Pogo Pins), and Pressure
Lifecycle / origin	Active / Taiwan, Republic of China
RoHS / REACH	RoHS3 Compliant / REACH Unaffected
ECCN / ESD	EAR99 / Static sensitive: Yes
Datasheet	seyunda.com/datasheet/Seyunda-SMD-Spring-Contacts-Datasheet.pdf
Product page	seyunda.com/type-8-01.html